

CERTIFICATE OF MAILING BY FIRST CLASS MAIL (37 CFR 1.8)

Applicant(s): Jonathan A. Noquil, et al.

Docket No.

90065.001400/17732.67130.00

Application No.

10/803,464

Filing Date

March 18, 2004

Examiner

Tuan Quach

Customer No.

34799

Group Art Unit

2826

Invention: **MULTI-FLIP CHIP ON LEAD FRAME ON OVER MOLDED IC PACKAGE AND METHOD
OF ASSEMBLY**

I hereby certify that this Amendment (7 pages)

(Identify type of correspondence)

is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to "Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450" [37 CFR 1.8(a)] on
July 22, 2005

(Date)

Kathleen A. Manczuk

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(Signature of Person Mailing Correspondence)

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Docket:
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IN THE UNITED STATES PATENT & TRADEMARK OFFICE

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|-------------|--|---|------------|
| Applicant: | Noquil, et al. |) | Examiner: |
| | |) | Tuan Quach |
| Serial No.: | 10/803,464 |) | |
| | |) | |
| Filed: | March 18, 2004 |) | Art Unit: |
| | |) | 2826 |
| For: | MULTI-FLIP CHIP ON LEAD FRAME ON OVER) | | |
| | MOLDED IC PACKAGE AND METHOD OF |) | |
| | ASSEMBLY |) | |

AMENDMENT

Mail Stop Amendment
Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

In response to the Office Action mailed February 25, 2005, please amend this application in the Claims as follows.

07/27/2005 BABRAHA1 00000027 10803464

02 FC:1201 400.00 OP